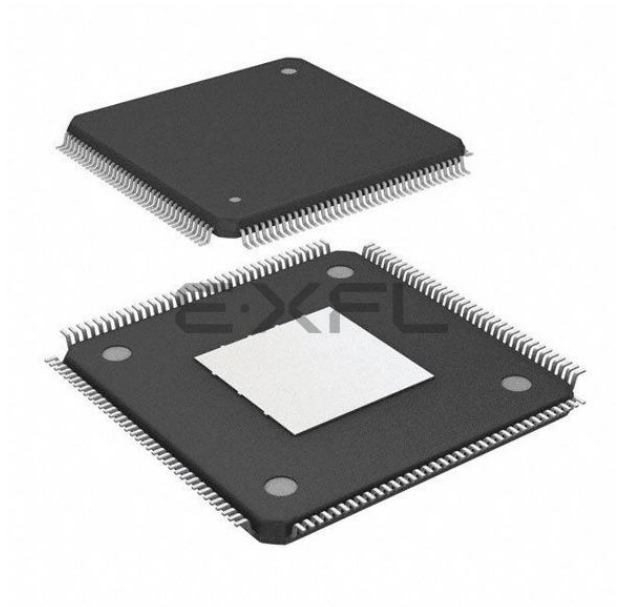

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Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	1395
Number of Logic Elements/Cells	22320
Total RAM Bits	608256
Number of I/O	79
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	144-LQFP Exposed Pad
Supplier Device Package	144-EQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce22e22i7

Chapter 9. SEU Mitigation in Cyclone IV Devices

Chapter 10. JTAG Boundary-Scan Testing for Cyclone IV Devices

Same-Port Read-During-Write Mode

This mode applies to a single-port RAM or the same port of a true dual-port RAM. In the same port read-during-write mode, there are two output choices: **New Data** mode (or flow-through) and **Old Data** mode. In **New Data** mode, new data is available on the rising edge of the same clock cycle on which it was written. In **Old Data** mode, the RAM outputs reflect the old data at that address before the write operation proceeds.

When using **New Data** mode together with `byteena`, you can control the output of the RAM. When `byteena` is high, the data written into the memory passes to the output (flow-through). When `byteena` is low, the masked-off data is not written into the memory and the old data in the memory appears on the outputs. Therefore, the output can be a combination of new and old data determined by `byteena`.

Figure 3–14 and Figure 3–15 show sample functional waveforms of same port read-during-write behavior with both **New Data** and **Old Data** modes, respectively.

Figure 3–14. Same Port Read-During Write: New Data Mode

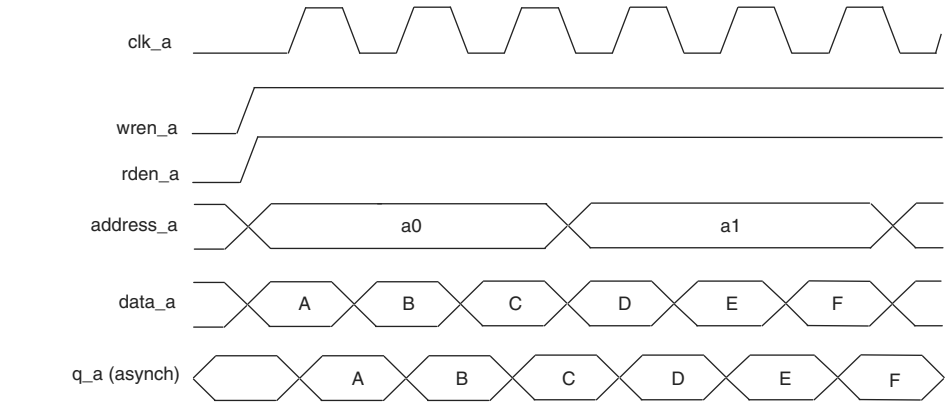
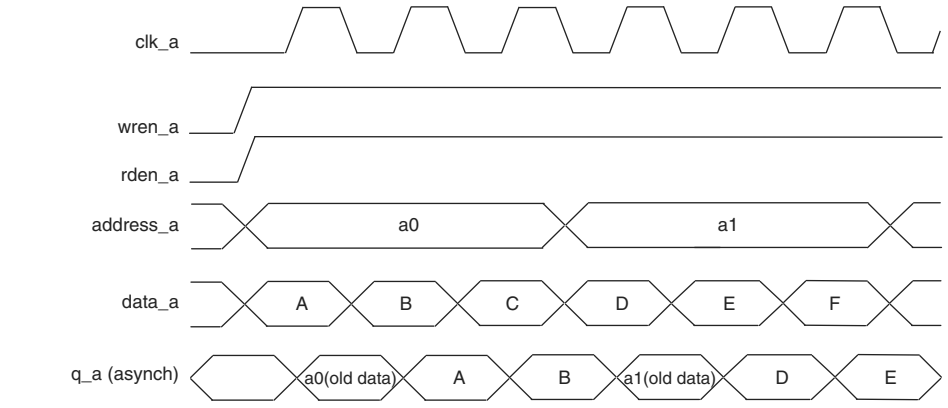


Figure 3–15. Same Port Read-During-Write: Old Data Mode



Mixed-Port Read-During-Write Mode

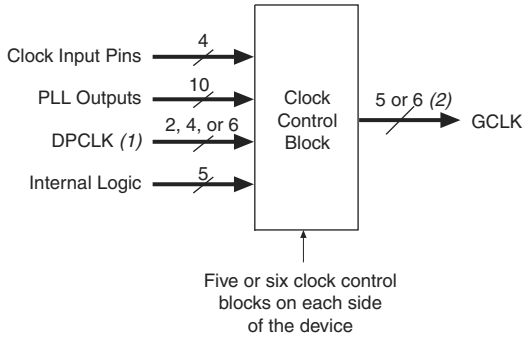
This mode applies to a RAM in simple or true dual-port mode, which has one port reading and the other port writing to the same address location with the same clock.

From the clock sources listed above, only two clock input pins, two out of four PLL clock outputs (two clock outputs from either adjacent PLLs), one DPCLK pin, and one source from internal logic can drive into any given clock control block, as shown in Figure 5–1 on page 5–11.

Out of these six inputs to any clock control block, the two clock input pins and two PLL outputs are dynamically selected to feed a GCLK. The clock control block supports static selection of the signal from internal logic.

Figure 5–5 shows a simplified version of the clock control blocks on each side of the Cyclone IV GX device periphery.

Figure 5–5. Clock Control Blocks on Each Side of Cyclone IV GX Device



Notes to Figure 5–5:

(1) The EP4CGX15 device has two DPCLK pins; the EP4CGX22 and EP4CGX30 devices have four DPCLK pins; the EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 devices have six DPCLK pins.

(2) Each clock control block in the EP4CGX15, EP4CGX22, and EP4CGX30 devices can drive five GCLK networks. Each clock control block in the EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 devices can drive six GCLK networks.

The inputs to the five clock control blocks on each side of the Cyclone IV E device must be chosen from among the following clock sources:

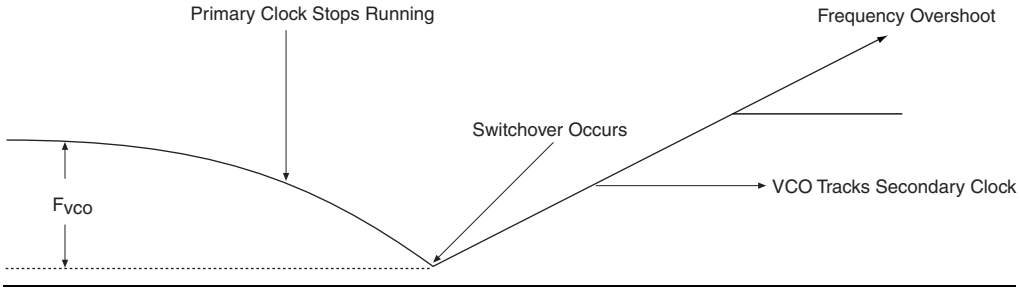
- Three or four clock input pins, depending on the specific device
- Five PLL counter outputs
- Two DPCLK pins and two CDPCLK pins from both the left and right sides and four DPCLK pins from both the top and bottom
- Five signals from internal logic

From the clock sources listed above, only two clock input pins, two PLL clock outputs, one DPCLK or CDPCLK pin, and one source from internal logic can drive into any given clock control block, as shown in Figure 5–1 on page 5–11.

Out of these six inputs to any clock control block, the two clock input pins and two PLL outputs are dynamically selected to feed a GCLK. The clock control block supports static selection of the signal from internal logic.

- When using manual clock switchover, the difference between `inclk0` and `inclk1` can be more than 20%. However, differences between the two clock sources (frequency, phase, or both) can cause the PLL to lose lock. Resetting the PLL ensures that the correct phase relationships are maintained between the input and output clocks.
- Both `inclk0` and `inclk1` must be running when the `clkswitch` signal goes high to start the manual clock switchover event. Failing to meet this requirement causes the clock switchover to malfunction.
- Applications that require a clock switchover feature and a small frequency drift must use a low-bandwidth PLL. When referencing input clock changes, the low-bandwidth PLL reacts slower than a high-bandwidth PLL. When the switchover happens, the low-bandwidth PLL propagates the stopping of the clock to the output slower than the high-bandwidth PLL. The low-bandwidth PLL filters out jitter on the reference clock. However, the low-bandwidth PLL also increases lock time.
- After a switchover occurs, there may be a finite resynchronization period for the PLL to lock onto a new clock. The exact amount of time it takes for the PLL to re-lock is dependent on the PLL configuration.
- If the phase relationship between the input clock to the PLL and output clock from the PLL is important in your design, assert `areset` for 10 ns after performing a clock switchover. Wait for the locked signal (or gated lock) to go high before re-enabling the output clocks from the PLL.
- Figure 5–20 shows how the VCO frequency gradually decreases when the primary clock is lost and then increases as the VCO locks on to the secondary clock. After the VCO locks on to the secondary clock, some overshoot can occur (an over-frequency condition) in the VCO frequency.

Figure 5–20. VCO Switchover Operating Frequency



- Disable the system during switchover if the system is not tolerant to frequency variations during the PLL resynchronization period. You can use the `clkbad0` and `clkbad1` status signals to turn off the PFD (`pfdena = 0`) so the VCO maintains its last frequency. You can also use the switchover state machine to switch over to the secondary clock. Upon enabling the PFD, output clock enable signals (`clkena`) can disable clock outputs during the switchover and resynchronization period. After the lock indication is stable, the system can re-enable the output clock or clocks.

Programmable Bandwidth

The PLL bandwidth is the measure of the PLL's ability to track the input clock and its associated jitter. PLLs of Cyclone IV devices provide advanced control of the PLL bandwidth using the programmable characteristics of the PLL loop, including loop filter and charge pump. The closed-loop gain 3-dB frequency in the PLL determines the PLL bandwidth. The bandwidth is approximately the unity gain point for open loop PLL response.

Phase Shift Implementation

Phase shift is used to implement a robust solution for clock delays in Cyclone IV devices. Phase shift is implemented with a combination of the VCO phase output and the counter starting time. The VCO phase output and counter starting time are the most accurate methods of inserting delays, because they are based only on counter settings that are independent of process, voltage, and temperature.

You can phase shift the output clocks from the PLLs of Cyclone IV devices in one of two ways:

- Fine resolution using VCO phase taps
- Coarse resolution using counter starting time

Fine resolution phase shifts are implemented by allowing any of the output counters (`C[4..0]`) or the M counter to use any of the eight phases of the VCO as the reference clock. This allows you to adjust the delay time with a fine resolution.

Equation 5–1 shows the minimum delay time that you can insert using this method.

Equation 5–1. Fine Resolution Phase Shift

$$\Phi_{fine} = \frac{T_{VCO}}{8} = \frac{1}{8f_{VCO}} = \frac{N}{8Mf_{REF}}$$

in which f_{REF} is the input reference clock frequency.

For example, if f_{REF} is 100 MHz, N = 1, and M = 8, then f_{VCO} = 800 MHz, and Φ_{fine} = 156.25 ps. The PLL operating frequency defines this phase shift, a value that depends on reference clock frequency and counter settings.

Coarse resolution phase shifts are implemented by delaying the start of the counters for a predetermined number of counter clocks. Equation 5–2 shows the coarse phase shift.

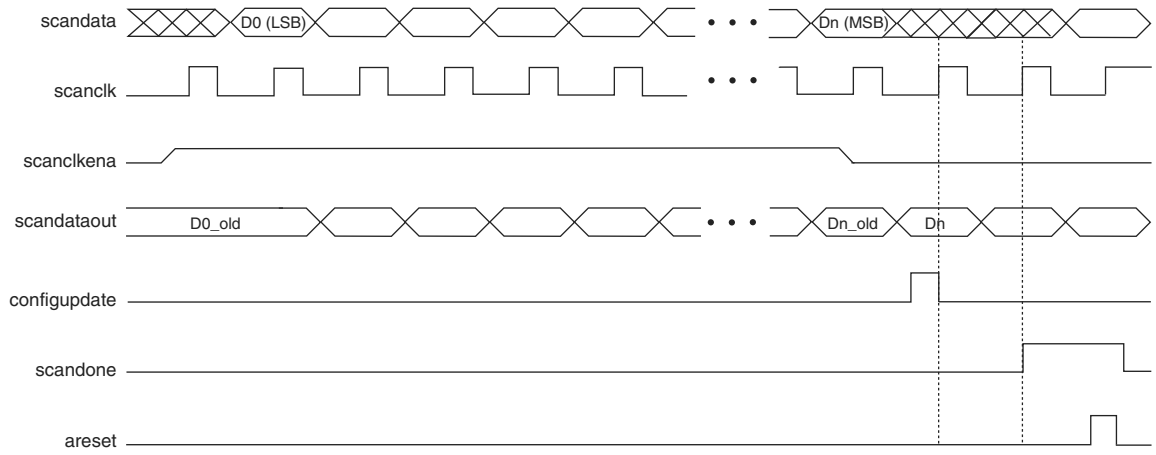
Equation 5–2. Coarse Resolution Phase Shift

$$\Phi_{coarse} = \frac{C-1}{f_{VCO}} = \frac{(C-1)N}{Mf_{REF}}$$

C is the count value set for the counter delay time (this is the initial setting in the PLL usage section of the compilation report in the Quartus II software). If the initial value is 1, *C* – 1 = 0° phase shift.

Figure 5–23 shows a functional simulation of the PLL reconfiguration feature.

Figure 5–23. PLL Reconfiguration Scan Chain



When reconfiguring the counter clock frequency, the corresponding counter phase shift settings cannot be reconfigured using the same interface. You can reconfigure phase shifts in real time using the dynamic phase shift reconfiguration interface. If you reconfigure the counter frequency, but wish to keep the same non-zero phase shift setting (for example, 90°) on the clock output, you must reconfigure the phase shift after reconfiguring the counter clock frequency.

Post-Scale Counters (C0 to C4)

You can configure multiply or divide values and duty cycle of post-scale counters in real time. Each counter has an 8-bit high time setting and an 8-bit low time setting. The duty cycle is the ratio of output high or low time to the total cycle time, that is the sum of the two. Additionally, these counters have two control bits, `rbypass`, for bypassing the counter, and `rselodd`, to select the output clock duty cycle.

When the `rbypass` bit is set to 1, it bypasses the counter, resulting in a divide by one. When this bit is set to 0, the PLL computes the effective division of the VCO output frequency based on the high and low time counters. For example, if the post-scale divide factor is 10, the high and low count values are set to 5 and 5, to achieve a 50–50% duty cycle. The PLL implements this duty cycle by transitioning the output clock from high-to-low on the rising edge of the VCO output clock. However, a 4 and 6 setting for the high and low count values, respectively, would produce an output clock with a 40–60% duty cycle.

The `rselodd` bit indicates an odd divide factor for the VCO output frequency with a 50% duty cycle. For example, if the post-scale divide factor is three, the high and low time count values are 2 and 1, respectively, to achieve this division. This implies a 67%–33% duty cycle. If you need a 50%–50% duty cycle, you must set the `rselodd` control bit to 1 to achieve this duty cycle despite an odd division factor. The PLL implements this duty cycle by transitioning the output clock from high-to-low on a falling edge of the VCO output clock. When you set `rselodd` = 1, subtract 0.5 cycles from the high time and add 0.5 cycles to the low time.

For example:

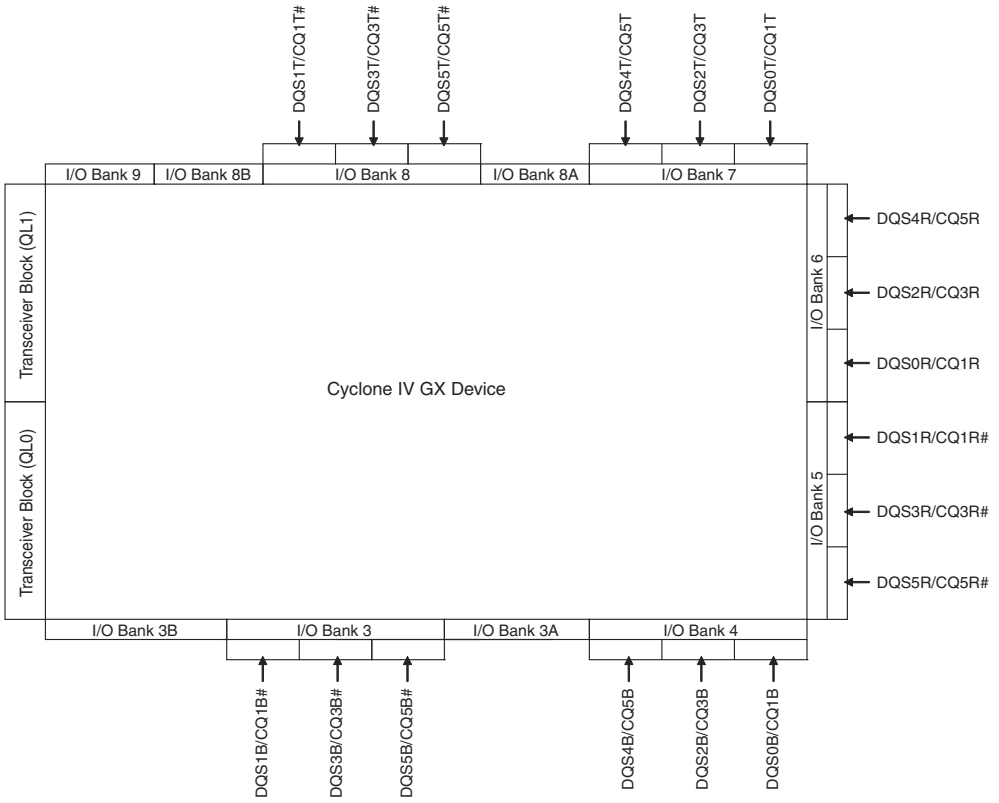
- High time count = 2 cycles

Table 6–3. Cyclone IV Devices Supported I/O Standards and Constraints (Part 2 of 3)

I/O Standard	Type	Standard Support	V_{CCIO} Level (in V)		Column I/O Pins			Row I/O Pins (1)	
			Input	Output	CLK, DQS	PLL_OUT	User I/O Pins	CLK, DQS	User I/O Pins
2.5-V LVTTL / LVCMOS	Single-ended	JESD8-5	3.3/3.0/2.5 (3)	2.5	✓	✓	✓	✓	✓
1.8-V LVTTL / LVCMOS	Single-ended	JESD8-7	1.8/1.5 (3)	1.8	✓	✓	✓	✓	✓
1.5-V LVCMOS	Single-ended	JESD8-11	1.8/1.5 (3)	1.5	✓	✓	✓	✓	✓
1.2-V LVCMOS (4)	Single-ended	JESD8-12A	1.2	1.2	✓	✓	✓	✓	✓
SSTL-2 Class I, SSTL-2 Class II	voltage-referenced	JESD8-9A	2.5	2.5	✓	✓	✓	✓	✓
SSTL-18 Class I, SSTL-18 Class II	voltage-referenced	JESD815	1.8	1.8	✓	✓	✓	✓	✓
HSTL-18 Class I, HSTL-18 Class II	voltage-referenced	JESD8-6	1.8	1.8	✓	✓	✓	✓	✓
HSTL-15 Class I, HSTL-15 Class II	voltage-referenced	JESD8-6	1.5	1.5	✓	✓	✓	✓	✓
HSTL-12 Class I	voltage-referenced	JESD8-16A	1.2	1.2	✓	✓	✓	✓	✓
HSTL-12 Class II (9)	voltage-referenced	JESD8-16A	1.2	1.2	✓	✓	✓	—	—
PCI and PCI-X	Single-ended	—	3.0	3.0	✓	✓	✓	✓	✓
Differential SSTL-2 Class I or Class II	Differential (5)	JESD8-9A	—	2.5	—	✓	—	—	—
			2.5	—	✓	—	—	✓	—
Differential SSTL-18 Class I or Class II	Differential (5)	JESD815	—	1.8	—	✓	—	—	—
			1.8	—	✓	—	—	✓	—
Differential HSTL-18 Class I or Class II	Differential (5)	JESD8-6	—	1.8	—	✓	—	—	—
			1.8	—	✓	—	—	✓	—
Differential HSTL-15 Class I or Class II	Differential (5)	JESD8-6	—	1.5	—	✓	—	—	—
			1.5	—	✓	—	—	✓	—
Differential HSTL-12 Class I or Class II	Differential (5)	JESD8-16A	—	1.2	—	✓	—	—	—
			1.2	—	✓	—	—	✓	—
PPDS (6)	Differential	—	—	2.5	—	✓	✓	—	✓
LVDS (10)	Differential	ANSI/TIA/EIA-644	2.5	2.5	✓	✓	✓	✓	✓
RSDS and mini-LVDS (6)	Differential	—	—	2.5	—	✓	✓	—	✓
BLVDS (8)	Differential	—	2.5	2.5	—	—	✓	—	✓

Figure 7–2 shows the location and numbering of the DQS, DQ, or CQ# pins in the Cyclone IV GX I/O banks.

Figure 7–2. DQS, CQ, or CQ# Pins in Cyclone IV GX I/O Banks *(1)*



Note to Figure 7–2:

(1) The DQS, CQ, or CQ# pin locations in this diagram apply to all packages in Cyclone IV GX devices except devices in 169-pin FBGA and 324-pin FBGA.

Altera recommends putting a buffer before the DATA and DCLK output from the master device to avoid signal strength and signal integrity issues. The buffer must not significantly change the DATA-to-DCLK relationships or delay them with respect to other AS signals (ASDI and nCS). Also, the buffer must only drive the slave devices to ensure that the timing between the master device and the serial configuration device is unaffected.

This configuration method supports both compressed and uncompressed **.sof**. Therefore, if the configuration bitstream size exceeds the capacity of a serial configuration device, you can enable the compression feature in the **.sof** or you can select a larger serial configuration device.

Guidelines for Connecting a Serial Configuration Device to Cyclone IV Devices for an AS Interface

For single- and multi-device AS configurations, the board trace length and loading between the supported serial configuration device and Cyclone IV device must follow the recommendations listed in Table 8–7.

Table 8–7. Maximum Trace Length and Loading for AS Configuration

Cyclone IV Device AS Pins	Maximum Board Trace Length from a Cyclone IV Device to a Serial Configuration Device (Inches)		Maximum Board Load (pF)
	Cyclone IV E	Cyclone IV GX	
DCLK	10	6	15
DATA[0]	10	6	30
nCSO	10	6	30
ASDO	10	6	30

Note to Table 8–7:

(1) For multi-devices AS configuration using Cyclone IV E with 1,0 V core voltage, the maximum board trace-length from the serial configuration device to the junction-split on both DCLK and Data0 line is 3.5 inches.

Estimating AS Configuration Time

AS configuration time is dominated by the time it takes to transfer data from the serial configuration device to the Cyclone IV device. This serial interface is clocked by the Cyclone IV device DCLK output (generated from a 40-MHz internal oscillator for Cyclone IV E devices, a 20- or 40-MHz internal oscillator, or an external CLKUSR of up to 40 MHz for Cyclone IV GX devices).

Equation 8–2 and Equation 8–3 show the configuration time calculations.

Equation 8–2.

$$\text{Size} \times \left(\frac{\text{maximum DCLK period}}{\text{1 bit}}\right) = \text{estimated maximum configuration ti}$$

Equation 8–3.

$$9{,}600{,}000 \text{ bits} \times \left(\frac{50 \text{ ns}}{\text{1 bit}}\right) = 480 \text{ ms}$$

JTAG instructions have precedence over any other configuration modes. Therefore, JTAG configuration can take place without waiting for other configuration modes to complete. For example, if you attempt JTAG configuration in Cyclone IV devices during PS configuration, PS configuration terminates and JTAG configuration begins. If the MSEL pins are set to AS mode, the Cyclone IV device does not output a DCLK signal when JTAG configuration takes place.

The four required pins for a device operating in JTAG mode are TDI, TDO, TMS, and TCK. All the JTAG input pins are powered by the V_{CCIO} pin and support the LVTTL I/O standard only. All user I/O pins are tri-stated during JTAG configuration. Table 8–14 explains the function of each JTAG pin.

Table 8–14. Dedicated JTAG Pins

Pin Name	Pin Type	Description
TDI	Test data input	Serial input pin for instructions as well as test and programming data. Data shifts in on the rising edge of TCK. If the JTAG interface is not required on the board, the JTAG circuitry is disabled by connecting this pin to V_{CC}. TDI pin has weak internal pull-up resistors (typically 25 kΩ).
TDO	Test data output	Serial data output pin for instructions as well as test and programming data. Data shifts out on the falling edge of TCK. The pin is tri-stated if data is not being shifted out of the device. If the JTAG interface is not required on the board, the JTAG circuitry is disabled by leaving this pin unconnected.
TMS	Test mode select	Input pin that provides the control signal to determine the transitions of the TAP controller state machine. Transitions in the state machine occur on the rising edge of TCK. Therefore, TMS must be set up before the rising edge of TCK. TMS is evaluated on the rising edge of TCK. If the JTAG interface is not required on the board, the JTAG circuitry is disabled by connecting this pin to V_{CC}. TMS pin has weak internal pull-up resistors (typically 25 kΩ).
TCK	Test clock input	The clock input to the BST circuitry. Some operations occur at the rising edge, while others occur at the falling edge. If the JTAG interface is not required on the board, the JTAG circuitry is disabled by connecting this pin to GND. The TCK pin has an internal weak pull-down resistor.

You can download data to the device through the USB-Blaster, MasterBlaster, ByteBlaster II, or ByteBlasterMV download cable, or the EthernetBlaster communications cable during JTAG configuration. Configuring devices with a cable is similar to programming devices in-system. Figure 8–23 and Figure 8–24 show the JTAG configuration of a single Cyclone IV device.

Table 1–13. Automatic RX Phase Compensation FIFO Read Clock Selection (Part 2 of 2)

Channel Configuration		Quartus II Selection
Bonded	With rate match FIFO (1)	`coreclkout` clock feeds the FIFO read clock for the bonded channels. `coreclkout` clock is the common bonded low-speed clock, which also feeds the FIFO read clock and transmitter PCS in the bonded channels.
	Without rate match FIFO	`rx_clkout` clock feeds the FIFO read clock. `rx_clkout` is forwarded through the receiver channel from low-speed recovered clock, which also feeds the FIFO write clock.

Note to Table 1–13:

(1) Configuration with rate match FIFO is supported in transmitter and receiver operation.

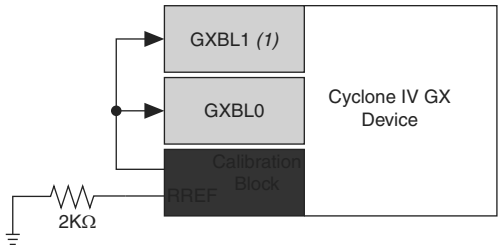
When using user-specified clock option, ensure that the clock feeding `rx_coreclk` port has 0 ppm difference with the RX phase compensation FIFO write clock.

Calibration Block

This block calibrates the OCT resistors and the analog portions of the transceiver blocks to ensure that the functionality is independent of process, voltage, and temperature (PVT) variations.

Figure 1–40 shows the location of the calibration block and how it is connected to the transceiver blocks.

Figure 1–40. Transceiver Calibration Blocks Location and Connection



Note to Figure 1–40:

(1) Transceiver block GXBL1 is only available for devices in F484 and larger packages.

Table 1–27. Receiver Ports in ALTGX Megafunction for Cyclone IV GX (Part 1 of 3)

Block	Port Name	Input/ Output	Clock Domain	Description
RX PCS	rx_syncstatus	Output	Synchronous to `tx_clkout` (non-bonded modes with rate match FIFO), `rx_clkout` (non-bonded modes without rate match FIFO), `coreclkout` (bonded modes), or `rx_coreclk` (when using the optional `rx_coreclk` input)	Word alignment synchronization status indicator. This signal passes through the RX Phase Compensation FIFO. ■ Not available in bit-slip mode
	rx_patternde tect	Output	Synchronous to `tx_clkout` (non-bonded modes with rate match FIFO), `rx_clkout` (non-bonded modes without rate match FIFO), `coreclkout` (bonded modes), or `rx_coreclk` (when using the optional `rx_coreclk` input)	Indicates when the word alignment logic detects the alignment pattern in the current word boundary. This signal passes through the RX Phase Compensation FIFO.
	rx_bitslip	Input	Asynchronous signal. Minimum pulse width is two parallel clock cycles.	Bit-slip control for the word aligner configured in bit-slip mode. ■ At every rising edge, word aligner slips one bit into the received data stream, effectively shifting the word boundary by one bit.
	rx_rlv	Output	Asynchronous signal. Driven for a minimum of two recovered clock cycles in configurations without byte serializer and a minimum of three recovered clock cycles in configurations with byte serializer.	Run-length violation indicator. ■ A high pulse indicates that the number of consecutive 1s or 0s in the received data stream exceeds the programmed run length violation threshold.
	rx_invpolarity	Input	Asynchronous signal. Minimum pulse width is two parallel clock cycles.	Generic receiver polarity inversion control. ■ A high level to invert the polarity of every bit of the 8- or 10-bit data to the word aligner.
	rx_enapattern align	Input	Asynchronous signal.	Controls the word aligner operation configured in manual alignment mode.
	rx_rmfifodata inserted	Output	Synchronous to `tx_clkout` (non-bonded modes) or `coreclkout` (bonded modes)	Rate match FIFO insertion status indicator. ■ A high level indicates the rate match pattern byte is inserted to compensate for the ppm difference in the reference clock frequencies between the upstream transmitter and the local receiver.
	rx_rmfifodata deleted	Output	Synchronous to `tx_clkout` (non-bonded modes) or `coreclkout` (bonded modes)	Rate match FIFO deletion status indicator. ■ A high level indicates the rate match pattern byte is deleted to compensate for the ppm difference in the reference clock frequencies between the upstream transmitter and the local receiver.

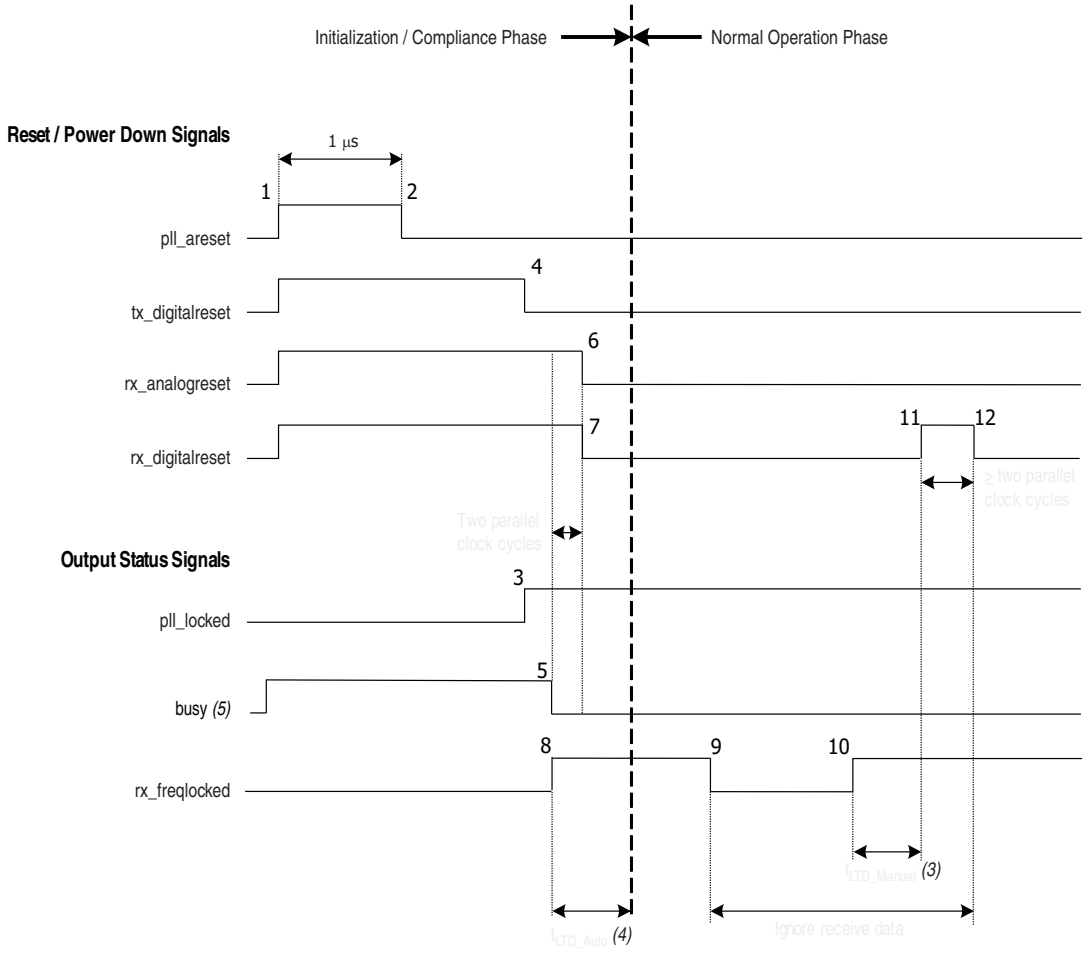
PCIe Functional Mode

You can configure PCIe functional mode with or without the receiver clock rate compensation FIFO in the Cyclone IV GX device. The reset sequence remains the same whether or not you use the receiver clock rate compensation FIFO.

PCIe Reset Sequence

The PCIe protocol consists of an initialization/compliance phase and a normal operation phase. The reset sequences for these two phases are described based on the timing diagram in Figure 2–10.

Figure 2–10. Reset Sequence of PCIe Functional Mode (1), (2)



Notes to Figure 2–10:

(1) This timing diagram is drawn based on the PCIe Gen 1 ×1 mode.

(2) For bonded PCIe Gen 1 ×2 and ×4 modes, there will be additional `rx_freqlocked[n]` signal. n=number of channels.

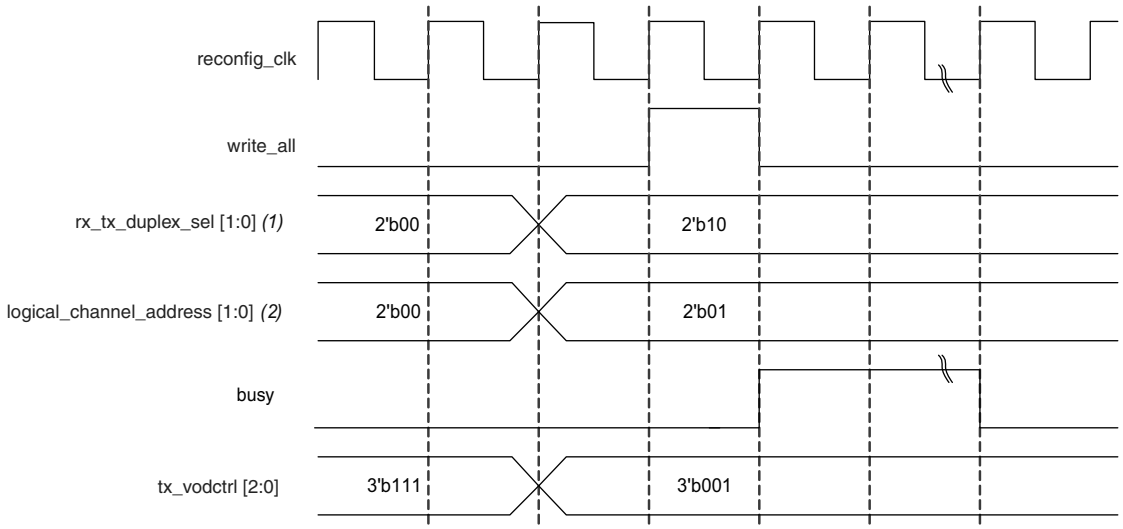
(3) For t_{LTD_Manual} duration, refer to the *Cyclone IV Device Datasheet* chapter.

(4) For t_{LTD_Auto} duration, refer to the *Cyclone IV Device Datasheet* chapter.

(5) The `busy` signal is asserted and deasserted only during initial power up when offset cancellation occurs. In subsequent reset sequences, the `busy` signal is asserted and deasserted only if there is a read or write operation to the ALTGX_RECONFIG megafunction.

Figure 3–4 shows the write transaction waveform for Method 1.

Figure 3–4. Write Transaction Waveform—Use 'logical_channel_address port' Option



Notes to Figure 3–4:

(1) In this waveform example, you are writing to only the transmitter portion of the channel.

(2) In this waveform example, the number of channels connected to the dynamic reconfiguration controller is four. Therefore, the `logical_channel_address` port is 2 bits wide.

Read Transaction

For example, to read the existing V_{OD} values from the transmit V_{OD} control registers of the transmitter portion of a specific channel controlled by the ALTGX_RECONFIG instance, perform the following steps:

1. Set the `logical_channel_address` input port to the logical channel address of the transceiver channel whose PMA controls you want to read (for example, `tx_vodctrl_out`).
2. Set the `rx_tx_duplex_sel` port to **2'b10** so that only the transmit PMA controls are read from the transceiver channel.
3. Ensure that the `busy` signal is low before you start a read transaction.
4. Assert the read signal for one `reconfig_clk` clock cycle. This initiates the read transaction.

The `busy` output status signal is asserted high to indicate that the dynamic reconfiguration controller is busy reading the PMA control values. When the read transaction has completed, the `busy` signal goes low. The `data_valid` signal is asserted to indicate that the data available at the read control signal is valid.

Internal Weak Pull-Up and Weak Pull-Down Resistor

Table 1–12 lists the weak pull-up and pull-down resistor values for Cyclone IV devices.

Table 1–12. Internal Weak Pull-Up and Weak Pull-Down Resistor Values for Cyclone IV Devices *(1)*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{\_PU}$	Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if you enable the programmable pull-up resistor option	V_{CCIO} = 3.3 V ± 5% *(2), (3)*	7	25	41	kΩ
		V_{CCIO} = 3.0 V ± 5% *(2), (3)*	7	28	47	kΩ
		V_{CCIO} = 2.5 V ± 5% *(2), (3)*	8	35	61	kΩ
		V_{CCIO} = 1.8 V ± 5% *(2), (3)*	10	57	108	kΩ
		V_{CCIO} = 1.5 V ± 5% *(2), (3)*	13	82	163	kΩ
		V_{CCIO} = 1.2 V ± 5% *(2), (3)*	19	143	351	kΩ
$R_{\_PD}$	Value of the I/O pin pull-down resistor before and during configuration	V_{CCIO} = 3.3 V ± 5% *(4)*	6	19	30	kΩ
		V_{CCIO} = 3.0 V ± 5% *(4)*	6	22	36	kΩ
		V_{CCIO} = 2.5 V ± 5% *(4)*	6	25	43	kΩ
		V_{CCIO} = 1.8 V ± 5% *(4)*	7	35	71	kΩ
		V_{CCIO} = 1.5 V ± 5% *(4)*	8	50	112	kΩ

Notes to Table 1–12:

(1) All I/O pins have an option to enable weak pull-up except the configuration, test, and JTAG pins. The weak pull-down feature is only available for JTAG TCK.

(2) Pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO}.

(3) $R_{\_PU} = (V_{CCIO} – V_I)/I_{R\_PU}$
Minimum condition: –40°C; $V_{CCIO} = V_{CC}$ + 5%, $V_I = V_{CC}$ + 5% – 50 mV;
Typical condition: 25°C; $V_{CCIO} = V_{CC}$, V_I = 0 V;
Maximum condition: 100°C; $V_{CCIO} = V_{CC}$ – 5%, V_I = 0 V; in which V_I refers to the input voltage at the I/O pin.

(4) $R_{\_PD} = V_I/I_{R\_PD}$
Minimum condition: –40°C; $V_{CCIO} = V_{CC}$ + 5%, V_I = 50 mV;
Typical condition: 25°C; $V_{CCIO} = V_{CC}$, $V_I = V_{CC}$ – 5%;
Maximum condition: 100°C; $V_{CCIO} = V_{CC}$ – 5%, $V_I = V_{CC}$ – 5%; in which V_I refers to the input voltage at the I/O pin.

Hot-Socketing

Table 1–13 lists the hot-socketing specifications for Cyclone IV devices.

Table 1–13. Hot-Socketing Specifications for Cyclone IV Devices

Symbol	Parameter	Maximum
$I_{IOPIN(DC)}$	DC current per I/O pin	300 µA
$I_{IOPIN(AC)}$	AC current per I/O pin	8 mA *(1)*
$I_{XCVRTX(DC)}$	DC current per transceiver TX pin	100 mA
$I_{XCVRRX(DC)}$	DC current per transceiver RX pin	50 mA

Note to Table 1–13:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, |IIOPIN| = C dv/dt, in which C is the I/O pin capacitance and dv/dt is the slew rate.

☞ During hot-socketing, the I/O pin capacitance is less than 15 pF and the clock pin capacitance is less than 20 pF.

I/O Timing

Use the following methods to determine I/O timing:

- the Excel-based I/O Timing
- the Quartus II timing analyzer

The Excel-based I/O timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get a timing budget estimation as part of the link timing analysis. The Quartus II timing analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after place-and-route is complete.

The Excel-based I/O Timing spreadsheet is downloadable from Cyclone IV Devices Literature website.

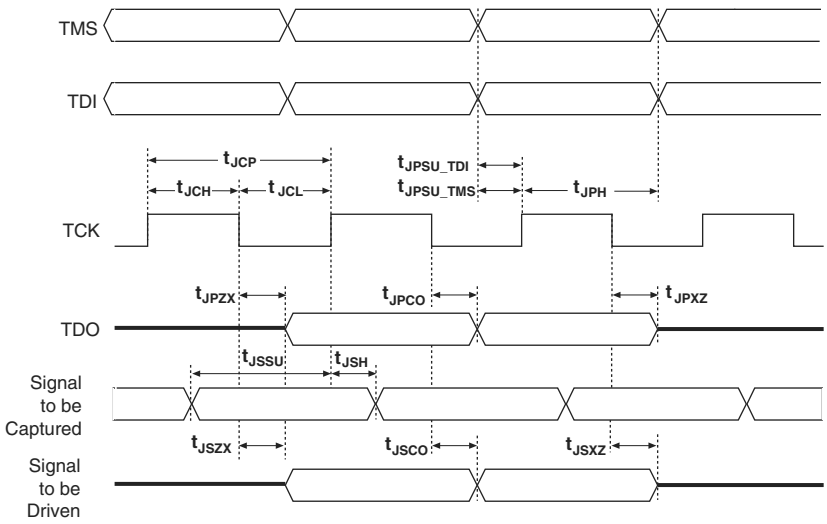
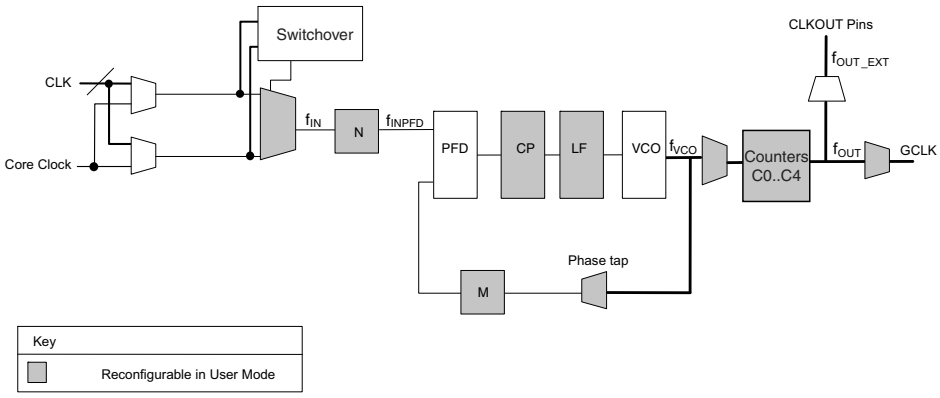
Glossary

Table 1–46 lists the glossary for this chapter.

Table 1–46. Glossary (Part 1 of 5)

Letter	Term	Definitions
A	—	—
B	—	—
C	—	—
D	—	—
E	—	—
F	f_{HSCLK}	High-speed I/O block: High-speed receiver/transmitter input and output clock frequency.
G	GCLK	Input pin directly to Global Clock network.
	GCLK PLL	Input pin to Global Clock network through the PLL.
H	HSIODR	High-speed I/O block: Maximum/minimum LVDS data transfer rate (HSIODR = 1/TUI).
I	Input Waveforms for the SSTL Differential I/O Standard	

Table 1–46. Glossary (Part 2 of 5)

Letter	Term	Definitions
J	JTAG Waveform	
K	—	—
L	—	—
M	—	—
N	—	—
O	—	—
P	PLL Block	The following highlights the PLL specification parameters: 
Q	—	—